

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S14 3	5982	(package or packaging).ti,ab,clm. and (electrode or lead or leadframe).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 16:49
S14 4	4171	(package or packaging).ti,ab,clm. and (electrode or lead or leadframe).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm. and (chip or ic or die).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 16:50
S14 5	157	(package or packaging).ti,ab,clm. and (electrode or lead or leadframe).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm. and (chip or ic or die).ti,ab,clm. and ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 16:50
S14 6	125	(package or packaging).ti,ab,clm. and (electrode or lead or leadframe).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm. and (chip or ic or die).ti,ab,clm. and ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area)).ti,ab,clm. and surface.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 17:00
S14 7	78	(package or packaging).ti,ab,clm. and (electrode or lead or leadframe).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm. and (chip or ic or die).ti,ab,clm. and ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area)).ti,ab,clm. and surface.ti,ab,clm. and (surface near10 (mount or mounting or mounted)).ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 16:58

S14 8	71	(package or packaging).ti,ab,clm. and ((electrode or lead or leadframe) near10 ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area))).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm. and (chip or ic or die).ti,ab,clm. and ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area)).ti,ab,clm. and surface.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 17:02
S14 9	21	(package or packaging).ti,ab,clm. and (((electrode or lead or leadframe) near10 ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area))) with (expose or exposing or exposed)).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm. and (chip or ic or die).ti,ab,clm. and ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area)).ti,ab,clm. and surface.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 17:04
S15 0	17	(package or packaging).ti,ab,clm. and (((electrode or lead or leadframe) near10 ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area))) with (expose or exposing or exposed) with surface).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm. and (chip or ic or die).ti,ab,clm. and ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area)).ti,ab,clm. and surface.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 17:06

S15 1	11	(package or packaging).ti,ab,clm. and (((electrode or lead or leadframe) near10 ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area)))) near10 (expose or exposing or exposed) near10 surface).ti,ab,clm. and (resin or epoxy).ti,ab,clm. and (mount or mounting or mounted).ti,ab,clm. and (chip or ic or die).ti,ab,clm. and ((thin or thinner or thick or thicker) near5 (portion or section or part or region or area)).ti,ab,clm. and surface.ti,ab,clm.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/03 17:12
----------	----	--	---	----	----	------------------